**Headline:** 10 Key Challenges in Electronics Thermal Design

**Text:** Miniaturization of electronics is continuing to increase power densities at all packaging levels. Miniaturization arises from cost reduction, being the key driver in many industry sectors, resulting in increasingly tighter design margins and less tolerance of over-design. This is particularly true in the physical design of the product, where over-design results in additional weight, volume, and in some cases manufacturing and assembly costs, increasing the cost of the final product.

**Image:** csr\_image\_150x150.png

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